

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT6300818

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
TIN POAY CHUAH	07/09/2020
BOK ENG CHEAH	07/09/2020
JACKSON CHUNG PENG KONG	07/09/2020
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	INTEL IP CORPORATION
<b>Street Address:</b>	2200 MISSION COLLEGE BOULEVARD
<b>City:</b>	SANTA CLARA
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	95054
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16887902
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Email:</b>	request@slwip.com
<b>Correspondent Name:</b>	SCHWEGMAN LUNDBERG & WOESSNER, P.A.
<b>Address Line 1:</b>	P.O. BOX 2938
<b>Address Line 4:</b>	MINNEAPOLIS, MINNESOTA 55402
<b>ATTORNEY DOCKET NUMBER:</b>	1884.776US1
<b>NAME OF SUBMITTER:</b>	COLE M. EHLERS
<b>SIGNATURE:</b>	/Cole M. Ehlers/
<b>DATE SIGNED:</b>	09/16/2020
<b>Total Attachments: 7</b>	
source=SIGNED1884776US1AssignmentSigned#page1.tif	
source=SIGNED1884776US1AssignmentSigned#page2.tif	
source=SIGNED1884776US1AssignmentSigned#page3.tif	
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RECORDATION FORM COVER SHEET  
PATENTS ONLY

Atty Ref/Docket No.: (AB9644-MY-US) 1884.776US1

Patent and Trademark Office

To the Director of the U.S. Patent and Trademark Office: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Tin Poay Chuah, Bok Eng Cheah, Jackson Chung Peng Kong

Additional name(s) of conveying party(ies) attached?

Yes  No

3. Nature of conveyance:

Assignment  Merger  
 Security Agreement  Change of Name  
 Other

Execution Date: July 9, 2020, July 9, 2020, July 9, 2020

2. Name and address of receiving party(ies):

Name: Intel Corporation

Street Address: 2200 Mission College Blvd.

City: Santa Clara State: CA Zip: 95054  
Country: United States of America

Additional name(s) & address(es) attached?  Yes  
 No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

Serial No. 16/887,902

B. Patent No.(s)

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Lea E. Westman

Address:

Schwegman Lundberg & Woessner, P.A.  
P.O. Box 2938  
Minneapolis, Minnesota 55402

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$ 0.00

Enclosed

Authorized to be charged to deposit account  
190743

8. Please charge any additional fees or credit any over payments to our Deposit Account No.: 190743

**DO NOT USE THIS SPACE**

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Lea E. Westman/Reg. No. 76,380

Name of Person Signing



Signature

9/11/20

Date

Total number of pages including cover sheet: 7

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents and Trademarks  
Mail Stop Assignment Recordation Services  
P.O. Box 1450  
Alexandria, VA 22313-1450

**PATENT**  
**REEL: 053785 FRAME: 0494**

## ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

<Tin Poay Chuah, Bok Eng Cheah, Jackson Chung Peng Kong>

hereby sell, assign, and transfer to:

### **Intel Corporation**

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

### **THREE DIMENSIONAL FOLDABLE SUBSTRATE WITH VERTICAL SIDE INTERFACE**

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on May 29, 2020 as

United States of America Application Number 16/887,902

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute

all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.



\_\_\_\_\_  
Tin Poay Chuah

9 July 2020

\_\_\_\_\_  
Date Signed

\_\_\_\_\_  
Bok Eng Cheah

\_\_\_\_\_  
Date Signed

\_\_\_\_\_  
Jackson Chung Peng Kong

\_\_\_\_\_  
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covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

_____ Tin Poay Chuah	_____ Date Signed
_____ <i>Bok Eng Cheah</i>	_____ 9 JULY 2020
_____ Bok Eng Cheah	_____ Date Signed
_____ Jackson Chung Peng Kong	_____ Date Signed

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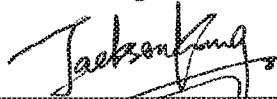
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\_\_\_\_\_  
Tin Poay Chuah

\_\_\_\_\_  
Date Signed

\_\_\_\_\_  
Bok Eng Cheah

\_\_\_\_\_  
Date Signed



9 July 2020

\_\_\_\_\_  
Jackson Chung Peng Long

\_\_\_\_\_  
Date Signed